

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) An apparatus for polishing one or more layers of a semiconductor device structure, comprising:
a polishing pad;
a subpad support located adjacent the polishing pad, the subpad support including a subpad retention element; and
a ~~substantially planar~~ subpad located between the subpad support and the polishing pad and removably secured to the subpad support by way of the subpad retention element while supporting the polishing pad without being secured thereto.
2. (Previously Presented) The apparatus of claim 1, wherein the polishing pad comprises one of a web format polishing pad and a belt format polishing pad.
3. (Withdrawn) The apparatus of claim 1, wherein the subpad retention element comprises a clamp configured to retain at least a portion of a periphery of the subpad.
4. (Previously Presented) The apparatus of claim 1, wherein the subpad retention element comprises negative pressure applicable to a bottom surface of the subpad through the subpad support.
5. (Withdrawn) The apparatus of claim 1, wherein the subpad retention element mechanically engages a complementary structure on or adjacent to a bottom surface of the subpad.

6. (Previously Presented) The apparatus of claim 1, further comprising a substantially rigid structure on a bottom surface of the subpad.
7. (Previously Presented) The apparatus of claim 6, wherein the substantially rigid structure is secured to the bottom surface of the subpad.
8. (Previously Presented) The apparatus of claim 6, wherein the substantially rigid structure comprises a polymer.
9. (Previously Presented) The apparatus of claim 6, wherein the substantially rigid structure comprises a metal.
10. (Previously Presented) The apparatus of claim 6, wherein the substantially rigid structure comprises a dense region of the subpad at the bottom surface thereof.
11. (Previously Presented) The apparatus of claim 1, wherein the subpad support comprises at least one lip configured to at least partially prevent lateral movement of a subpad assembled with and secured to the subpad support.
12. (Previously Presented) The apparatus of claim 11, wherein the at least one lip substantially completely laterally surrounds a peripheral edge of the subpad.
13. (Previously Presented) The apparatus of claim 1, wherein a bottom surface of the subpad is substantially free of adhesive material.
14. (Original) The apparatus of claim 1, including a subpad access element.
15. (Previously Presented) The apparatus of claim 14, wherein the subpad access element is configured to at least partially move the polishing pad away from the subpad support.

16. (Previously Presented) The apparatus of claim 14, wherein the subpad access element moves a polishing pad support so as to at least partially move the polishing pad away from the subpad support.

17. (Currently amended) A subpad support for use in an apparatus for polishing one or more layers of a semiconductor device structure and that includes a polishing pad that is movable independently from the subpad support, the subpad support comprising a subpad retention element for removably retaining a substantially planar subpad which is configured to support at least a portion of ~~a-the~~ polishing pad of the apparatus ~~but not configured to be secured relative to the polishing pad.~~

18. (Previously Presented) The subpad support of claim 17, wherein the subpad retention element is configured to removably retain the subpad.

19. (Withdrawn) The subpad support of claim 17, wherein the subpad retention element mechanically engages a corresponding feature on or adjacent to a bottom surface of the subpad.

20. (Previously Presented) The subpad support of claim 17, wherein the subpad retention element is configured to apply a negative pressure to a bottom surface of the subpad.

21. (Withdrawn) The subpad support of claim 17, wherein the subpad retention element comprises a clamp element configured to engage at least a portion of a periphery of a subpad assembled with the subpad support.

22. (Original) The subpad support of claim 17, comprising a lip configured to at least partially prevent lateral movement of a subpad assembled with the subpad support.

23. (Previously Presented) The subpad support of claim 22, wherein the lip is configured to substantially completely surround a peripheral edge of the subpad.

24-39. (Cancelled)

40. (Previously Presented) An apparatus for polishing one or more layers of a semiconductor device structure, comprising:
a polishing pad;
a subpad support located adjacent the polishing pad, the subpad support including a substantially planar subpad support surface and a subpad retention element associated with the subpad support surface; and
a subpad disposed on the subpad support surface so as to be positionable between the subpad support and the polishing pad without being secured to the polishing pad, the subpad retention element being configured to removably secure the subpad support on the subpad support surface.

41. (Previously Presented) The apparatus of claim 40, wherein the subpad retention element comprises negative pressure applicable to a backing of the subpad through the subpad support.

42. (Withdrawn) The apparatus of claim 40, wherein the subpad retention element mechanically engages a complementary structure on or adjacent to a bottom surface of the subpad.

43. (Previously Presented) The apparatus of claim 40, wherein the subpad support comprises at least one lip configured to at least partially prevent lateral movement of a subpad assembled with and secured to the subpad support.

44. (Previously Presented) The apparatus of claim 43, wherein the at least one lip substantially completely laterally surrounds a peripheral edge of the subpad.

45. (Previously Presented) The apparatus of claim 40, wherein a backing of the subpad is substantially free of adhesive material.

46. (Previously Presented) The apparatus of claim 40, including a subpad access element.

47. (Previously Presented) The apparatus of claim 46, wherein the subpad access element is configured to at least partially move the polishing pad away from the subpad support.

48. (Previously Presented) The apparatus of claim 46, wherein the subpad access element moves a polishing pad support so as to at least partially move the polishing pad away from the subpad support.

49. (Currently amended) A subpad support assembly for use in an apparatus for polishing one or more layers of a semiconductor device structure, comprising:
a subpad configured to support a polishing pad without being secured to the polishing pad;
a substantially planar-support surface configured to receive a subpad; and
a subpad retention element associated with the support surface so as to retain the subpad in position thereon so as to support a polishing pad of the apparatus without being secured to the polishing pad.

50. (Currently amended) The subpad support assembly of claim 49, wherein the subpad retention element is configured to removably retain the subpad.

51. (Withdrawn and currently amended) The subpad support assembly of claim 49, wherein the subpad retention element mechanically engages a corresponding feature on or adjacent to a bottom surface of the subpad.

52. (Currently amended) The subpad support assembly of claim 49, comprising wherein the subpad retention element is configured to at least partially prevent lateral movement of the subpad.

53. (Currently amended) The subpad support assembly of claim 52, wherein the subpad retention element is configured to substantially completely surround a peripheral edge of the subpad.

54. (Currently amended) The subpad support assembly of claim 49, wherein the subpad retention element is configured to apply a negative pressure to a bottom surface of the subpad.